

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1	("6198976").PN.	US-PGPUB; USPAT	OR	OFF	2005/10/17 16:00
S1	0	(sens\$3 with compar\$3 with line with position\$4 with (wafer substrate workpiece semiconductor)) and (118/715-733.ccls. 156/345.\$ccls. 414/935-941.ccls.)	US-PGPUB; USPAT	OR	ON	2004/08/08 17:30
S2	3	(compar\$3 with line with position\$4 with (wafer substrate workpiece semiconductor)) and (118/715-733.ccls. 156/345.\$ccls. 414/935-941.ccls.)	US-PGPUB; USPAT	OR	ON	2004/08/08 17:33
S3	206	(compar\$3 with line with position\$4 with (wafer substrate workpiece semiconductor))	US-PGPUB; USPAT	OR	ON	2004/08/08 17:31
S4	4	(compar\$3 with line with position\$4 with (wafer substrate workpiece semiconductor)) same (transfer\$4 convey\$4 transport\$4)	US-PGPUB; USPAT	OR	ON	2004/08/08 17:33
S5	206	(compar\$3 with line with position\$4 with (wafer substrate workpiece semiconductor))	US-PGPUB; USPAT	OR	ON	2004/08/08 17:35
S6	3	(compar\$3 with line with position\$4 with (wafer substrate workpiece semiconductor)) same (transfer\$4 convey\$4 transport\$4)	EPO; JPO; DERWENT	OR	ON	2004/08/08 17:33
S7	99	((sens\$3 detect\$3 measur\$3) with compar\$3 with line with position\$4 with (wafer substrate workpiece semiconductor))	US-PGPUB; USPAT	OR	ON	2004/08/08 17:36
S8	105	((sens\$3 detect\$3 measur\$3) with compar\$3 with line with align\$4 position\$4) with (wafer substrate workpiece semiconductor))	US-PGPUB; USPAT	OR	ON	2004/08/08 17:39
S9	321	(414/936).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/08/08 17:39
S10	244	S9 and (sens\$3 detect\$3)	US-PGPUB; USPAT	OR	ON	2004/08/08 17:40
S11	199	S9 and ((sens\$3 detect\$3) with (position\$3 align\$3))	US-PGPUB; USPAT	OR	ON	2004/08/08 17:40
S12	23	S9 and ((sens\$3 detect\$3) with (position\$3 align\$3) with compar\$4)	US-PGPUB; USPAT	OR	ON	2004/08/08 17:40
S13	1819	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/08/08 17:28
S14	31	((((118/719) or (414/939) or (156/345.31) or (156/345.32)). CCLS.) and 156/345.24.ccls.	US-PGPUB; USPAT	OR	ON	2003/12/12 18:38
S15	322	((((118/719) or (414/939) or (156/345.31) or (156/345.32)). CCLS.) and ((position\$3 align\$4) with (detect\$3 sens\$3 monitor\$3 sens\$3))	US-PGPUB; USPAT	OR	ON	2003/12/12 18:39
S16	1757	(118/715-733.ccls. 156/345.\$ccls. 414/935-941.ccls.) and ((position\$3 align\$4) with (detect\$3 sens\$3 monitor\$3 sens\$3))	US-PGPUB; USPAT	OR	ON	2003/12/12 18:39
S17	43	(118/715-733.ccls. 156/345.\$ccls. 414/935-941.ccls.) and ((position\$3 align\$4) with (detect\$3 sens\$3 monitor\$3 sens\$3) with (inlet entry entrance))	US-PGPUB; USPAT	OR	ON	2003/12/12 18:40
S18	3	("5483138") or ("5917601") or ("6004047")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/12/18 18:25
S19	1	("5512320").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/12/18 18:42
S20	1827	((118/719) or (414/939) or (156/345.31) or (156/345.32)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/12/18 18:43
S21	331	((((118/719) or (414/939) or (156/345.31) or (156/345.32)). CCLS.) and ((position\$3 align\$3) with (sens\$3 detect\$3 monitor\$3 observ\$5))	US-PGPUB; USPAT	OR	ON	2003/12/18 19:36

S22	384	((156/345.13) or (156/345.15) or (156/345.24)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2003/12/18 18:50
S23	58	tamura-naoyuki.in.	US-PGPUB; USPAT	OR	ON	2005/04/16 20:08
S24	214	c23c016\$.ipc. and ((position\$3 align\$3) with (sens\$3 detect\$3 monitor\$3 observ\$5))	EPO; JPO; DERWENT	OR	ON	2003/12/18 19:36
S28	20	(US-20030023343-\$ or US-20030168173-\$ or US-20040074603-\$ or US-20040151574-\$).did. or (US-4507078-\$ or US-4618292-\$ or US-4643579-\$ or US-4654106-\$ or US-4819167-\$ or US-4836733-\$ or US-5452521-\$ or US-5483138-\$ or US-5512320-\$ or US-5814196-\$ or US-5917601-\$ or US-5980194-\$ or US-6166509-\$ or US-6368183-\$ or US-6370793-\$ or US-6553280-\$).did.	US-PGPUB; USPAT	OR	ON	2004/11/10 17:39
S29	65	tamura-naoyuki.in.	US-PGPUB; USPAT	OR	ON	2005/04/16 20:08
S30	2	10/218,406	US-PGPUB; USPAT	OR	ON	2005/10/17 16:00
S31	484	(414/805.ccls. 414/217.ccls.) and ((wafer substrate semiconductor workpiece) with (align\$4 orient\$4))	US-PGPUB; USPAT	OR	ON	2005/10/16 20:05
S32	74	(414/805.ccls. 414/217.ccls.) and ((wafer substrate semiconductor workpiece) with (align\$4 orient\$4) with (sens\$4 detect\$4 measur\$4 observ\$4))	US-PGPUB; USPAT	OR	ON	2005/10/16 20:05
S33	105	(414/805.ccls. 414/217.ccls.) and ((wafer substrate semiconductor workpiece) with (align\$4 orient\$4) with (sens\$4 detect\$4 measur\$4 observ\$4 control\$4))	US-PGPUB; USPAT	OR	ON	2005/10/16 20:05
S34	46	(414/805.ccls. 414/217.ccls.) and ((wafer substrate semiconductor workpiece) with (align\$4 orient\$4) with (sens\$4 detect\$4 measur\$4 observ\$4 control\$4) with (transfer\$4 translat\$4 convey\$4 mov\$4))	US-PGPUB; USPAT	OR	ON	2005/10/16 20:06
S35	5	("5706930").URPN.	USPAT	OR	ON	2005/10/16 20:15
S36	45	("3907439" "3945505" "4024944" "4148344" "4201378" "4228886" "4449885" "4457664" "4466073" "4507078" "4523985" "4559451" "4635373" "4647266" "4698511" "4705951" "4720635" "4744713" "4765793" "4770590" "4789294" "4818169" "4819167" "4833790" "4836733" "4880348" "4907035" "5044752" "5162642" "5194743" "5239182" "5483138" "5706201" "5706930" "5721607" "5740062" "5768125" "5822213" "5870488" "5905850" "5917601" "5980194" "5995234" "6198976" "6327517").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/16 20:16
S37	56	("5483138").URPN.	USPAT	OR	ON	2005/10/16 20:29